

ABSTRACT

A support piece formation laminate film according to the present disclosure includes a base material film, an adhesive layer, and a support piece formation film, in this order, in which the support piece formation film has a multi-layer structure including at least resin layer having a tensile elastic modulus of 8.0 MPa or more. The support piece formation laminate film is applied to a manufacturing process of a semiconductor device having a dolmen structure including a substrate, a first chip disposed on the substrate, a plurality of support pieces disposed around the first chip, on the substrate, and a second chip disposed to be supported by the plurality of support pieces and to cover the first chip.

Fig. 1